

14 Leads - SOIC
Package Material Declaration



Date	10-Jul-17	Product name	Integrated Circuit
Package Code	DC	RoHS Compliant	Y
Package Name	Plastic Small Outline 150mil	Halogen Free	Y
Product Total Mass (g)	0.13862	Plating	Pure Matte Sn

Product Number TH8056

Material Declaration

Part Name	Material Name	Component Weight (g)	Material Component (Element)	CAS #	Element ratio (%)	Material Weight (g)	Ratio total Wt (ppm)
Leadframe	High Copper Alloy C194	0.0486	Copper (Cu)	7440-50-8	97.15	0.04726	340895
			Iron (Fe)	7439-89-6	2.5	0.00122	8772
			Phosphorus (P)	7723-14-0	0.15	0.00007	526
			Zinc (Zn)	7440-66-6	0.2	0.00010	702
Leadframe Plating	Ag Ring Plating	0.0005	Silver Ag	7440-22-4	100	0.00049	3535
Die	Silicon IC	0.0036	Silicon (Si)	7440-21-3	99.99	0.00360	25967
			others	-	0.01	0.0000004	3
Die attach material	Conductive epoxy 84LMISR4	0.0011	Silver (70-85)	7440-22-4	80	0.00089	6406
			Epoxy Resin (5~25%)	Proprietary	15	0.00017	1201
			Aromatic amine (1-10)	Proprietary	5	0.00006	400
Wire	Gold	0.0005	Gold (Au)	7440-57-5	99.99	0.00049	3535
			Dopant	Trade Secret	0.01	0.00000005	0.4
Lead Finish	Tin	0.0026	Tin (Sn)	7440-31-5	99.99	0.00256	18468
			others	7439-92-1	0.01	0.0000003	2
Encapsulation	G600C	0.0817	Silica fused (75~95%)	60676-86-0	87.7	0.07168	517068
			Epoxy Resin (2~8%)	Proprietary	5	0.00409	29479
			Epoxy, Cresol Novolac (1~3%)	29690-82-2	2	0.00163	11792
			Phenol Resin (2~8%)	Proprietary	5	0.00409	29479
			Carbon Black (0.1~0.5%)	1333-86-4	0.3	0.00025	1769

Total package weight (g) 0.13862

Comments

- Composition derived from MSDS and material CoC from vendors
- Component weight based on assembly of generic parts
- Reliability qualification reports are available upon request through the appropriate sales or marketing contact
- Third party testing for RoHS substances are available upon request to environment@melexis.com

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